



## ADVANCED 8-PIN LOAD-SHARE CONTROLLER

### FEATURES

- High Accuracy, Better Than 1% CurrentShare Error at Full Load
- High-Side or Low-Side (GND Reference) Current-Sense Capability
- Ultra-Low Offset Current Sense Amplifier
- Single Wire Load Share Bus
- Full Scale Adjustability
- Intel® SSI LoadShare Specification Compliant
- Disconnect from Load Share Bus at Stand-By
- Load Share Bus Protection Against Shorts to GND or to the Supply Rail
- 8-Pin MSOP Package Minimizes Space
- Lead-Free Assembly

### SYSTEM CONFIGURATIONS

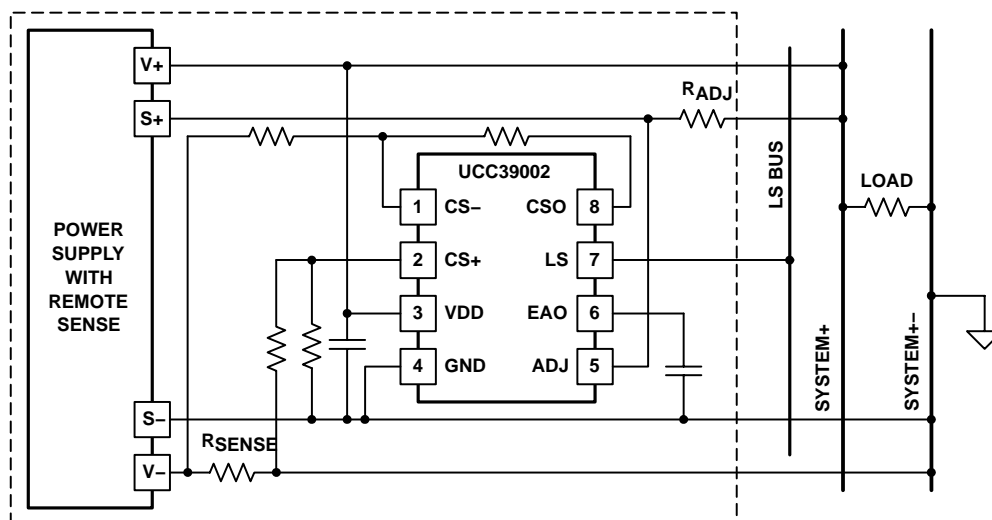
- Modules With Remote Sense Capability
- Modules With Adjust Input
- Modules With Both Remote Sense and Adjust Input
- In Conjunction With the Internal Feedback E/A of OEM Power Supply Units

### DESCRIPTION

The UCC39002 is an advanced, high performance and low cost loadshare controller that provides all necessary functions to parallel multiple independent power supplies or dc-to-dc modules. Targeted for high reliability applications in server, workstation, telecom and other distributed power systems, the controller is suitable for N+1 redundant systems or high current applications where off-the-shelf power supplies need to be paralleled.

The BiCMOS UCC39002 is based on the automatic master/slave architecture of the UC3902 and UC3907 load share controllers. It provides better than 1% current share error between modules at full load by using a very low offset post-package-trimmed current-sense amplifier and a high-gain negative feedback loop. And with the amplifier's common mode range of 0-V to the supply rail, the current sense resistor can be placed in either the GND return path or in the positive output rail of the power supply.

### TYPICAL LOW-SIDE CURRENT SENSING APPLICATION



## DESCRIPTION (continued)

During transient conditions while adding or removing power supplies, the UCC39002 protects the system by keeping the load share bus disconnected from the remaining supplies. By disabling the adjust function in case a short of the load share bus occurs to either GND or the supply rail, it also provides protection for the system against erroneous output voltage adjustment.

The UCC39002 also meets Intel's SSI (Server System Infrastructure) loadshare specifications of a single-line load share bus and scalable load share voltage for any level of output currents.

The UCC39002 family is offered in 8-pin MSOP (DGK), SOIC (D), and PDIP (P) packages.

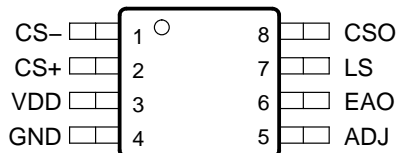
### absolute maximum ratings over operating free-air temperature (unless otherwise noted)<sup>†§</sup>

Supply voltage, current limited ( $V_{DD}$ )	–0.3 V to 15 V
Supply voltage, voltage source ( $V_{DD}$ )	–0.3 V to 13.5 V
Input voltage, current sense amplifier ( $V_{CS+}$ , $V_{CS-}$ )	–0.3 V to $V_{DD} + 0.3$ V
Current sense amplifier output voltage ( $V_{CSO}$ )	–0.3 V to $V_{DD}$
Load share bus voltage ( $V_{LS}$ )	–0.3 V to $V_{DD}$
Supply current ( $I_{DD} + I_{ZENER}$ )	10 mA
Adjust pin input voltage ( $V_{ADJ}$ )	$V_{EAO} + 1 \text{ V} < V_{ADJ} \leq V_{DD}$
Adjust pin sink current ( $I_{ADJ}$ )	6 mA
Operating junction temperature range, $T_J$	–55°C to 150°C
Storage temperature range $T_{stg}$	–65°C to 150°C
Lead Temperature, $T_{sol}$ (Soldering, 10 seconds)	300°C

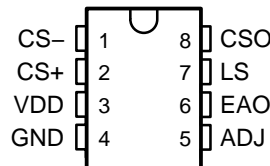
<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>§</sup> All voltages are with respect to GND. Currents are positive into, negative out of the specified terminal.

**SOIC (D) OR MSOP (DGK) PACKAGE**  
(TOP VIEW)



**PDIP (P) PACKAGE**  
(TOP VIEW)



### AVAILABLE OPTIONS

$T_A = T_J$	PACKAGED DEVICES		
	SOIC–8 (D) <sup>†</sup>	MSOP–8 (DGK) <sup>†</sup>	PDIP–8 (P)
–40°C to 105°C	UCC29002D	UCC29002DGK	UCC29002P
0°C to 70°C	UCC39002D	UCC39002DGK	UCC39002P

<sup>†</sup> The D and DGK packages are available taped and reeled. Add R suffix to device type (e.g. UCC39002DR) to order quantities of 2,500 devices per reel.

electrical characteristics  $V_{DD} = 12\text{ V}$ ,  $0^{\circ}\text{C} < T_A < 70^{\circ}\text{C}$  for the UCC39002,  $-40^{\circ}\text{C} < T_A < 105^{\circ}\text{C}$  for the UCC29002,  $T_A = T_J$  (unless otherwise noted)

## general

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Supply current	LS with no load, $ADJ = 5\text{ V}$		2.5	3.5	mA
$V_{DD}$ clamp voltage	$I_{DD} = 6\text{ mA}$	13.50	14.25	15.00	V

## undervoltage lockout

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Start-up voltage <sup>(1)</sup>		4.175	4.375	4.575	V
Hysteresis		0.200	0.375	0.550	

## current sense amplifier

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNITS
V <sub>IO</sub>	Input offset voltage	T <sub>A</sub> = 25°C V <sub>IC</sub> = 0.5 V or 11.5 V, V <sub>CSO</sub> = 5 V	−100		100	μV
		Over-temperature variation		±10		μV/°C
A <sub>V</sub>	Gain		75	90		dB
CMRR	Common mode rejection ratio		75	90		
I <sub>BIAS</sub>	Input bias current (CS+, CS−)		−0.6		0.6	μA
V <sub>OH</sub>	High-level output voltage (CSO)	0.1 V ≤ ([CS+] − [CS−]) ≤ 0.4 V, I <sub>OUT_CS0</sub> = 0 mA	10.7	11.0	11.8	V
V <sub>OL</sub>	Low-level output voltage (CSO)	−0.4 V ≤ ([CS+] − [CS−]) ≤ 0.1 V, I <sub>OUT_CS0</sub> = 0 mA	0.00	0.10	0.15	
I <sub>OH</sub>	High-level output current (CSO)	V <sub>CSO</sub> = 10 V	−1	−1.5		mA
I <sub>OL</sub>	Low-level output current (CSO)	V <sub>CSO</sub> = 1 V	1	1.5		
GBW	Gain bandwidth product <sup>(2)</sup>			2		MHz

## load share driver (LS)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNITS
V <sub>RANGE</sub>	Input voltage range		0		10	V
V <sub>OUT</sub>	Output voltage	V <sub>CSO</sub> = 1 V	0.995	1	1.005	
		V <sub>CSO</sub> = 10 V	9.995	10	10.005	
V <sub>OL</sub>	Low-level output voltage	V <sub>CSO</sub> = 0 V, I <sub>OUT_LS</sub> = 0 mA	0.00	0.10	0.15	
V <sub>OH</sub>	High-level output voltage <sup>(2)</sup>		V <sub>DD</sub> -1.7			
I <sub>OUT</sub>	Output current	0.5 V ≤ V <sub>LS</sub> ≤ 10 V	-1	-1.5		mA
I <sub>SC</sub>	Short circuit current	V <sub>LS</sub> = 0 V, V <sub>CSO</sub> = 10 V	-10	-20		
V <sub>SHTDN</sub>	Driver shutdown threshold	V <sub>CS-</sub> - V <sub>CS+</sub>	0.3	0.5	0.7	V

## load share bus protection

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNITS
I <sub>ADJ</sub>	Adjust amplifier current	V <sub>CSO</sub> = 2 V, V <sub>EAO</sub> = 2 V,	V <sub>LS</sub> = V <sub>DD</sub> , V <sub>ADJ</sub> = 5 V	0	5	10	μA
		V <sub>CSO</sub> = 2 V, V <sub>EAO</sub> = 2 V,	V <sub>LS</sub> = 0 V, V <sub>ADJ</sub> = 5 V	0	5	10	

(1) Enables the load share bus at start-up.

(2) Ensured by design. Not production tested.

electrical characteristics  $V_{DD} = 12\text{ V}$ ,  $0^{\circ}\text{C} < T_A < 70^{\circ}\text{C}$  for the UCC39002,  $-40^{\circ}\text{C} < T_A < 105^{\circ}\text{C}$  for the UCC29002,  $T_A = T_J$  (unless otherwise noted) (continued)

### error amplifier

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNITS
$V_{OH}$	High-level output voltage	$I_{OUT\_EAO} = 0\text{ mA}$	3.50	3.65	3.80	V
gm	Transconductance	$I_{EAO} = \pm 50\text{ }\mu\text{A}$		14		mS
$I_{OH}$	High-level output current	$V_{LS} - V_{CSO} = 0.4\text{ V}$ , $V_{EAO} = 2.2\text{ k}\Omega$	0.70	0.85	1.00	mA

### ADJ buffer

PARAMETER			TEST CONDITIONS		MIN	TYP	MAX	UNITS
$V_{IO}$	Input offset voltage <sup>(2)</sup>		$V_{ADJ} = 1.5\text{ V}$ , $V_{EAO} = 0\text{ V}$ ,			-60		mV
$I_{SINK}$	Sink current		$V_{ADJ} = 5.0\text{ V}$ , $V_{EAO} = 0\text{ V}$		0	5	10	$\mu\text{A}$
$I_{SINK}$	Sink current	$T_A = 25^{\circ}\text{C}$	$V_{ADJ} = 5.0\text{ V}$ , $LS = \text{floating}$ , $V_{EAO} = 2.0\text{ V}$		3.60	3.95	4.30	mA
		$0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$			3.45	3.95	4.45	
		$-40^{\circ}\text{C} \leq T_A \leq 105^{\circ}\text{C}$			3.35	3.95	4.55	

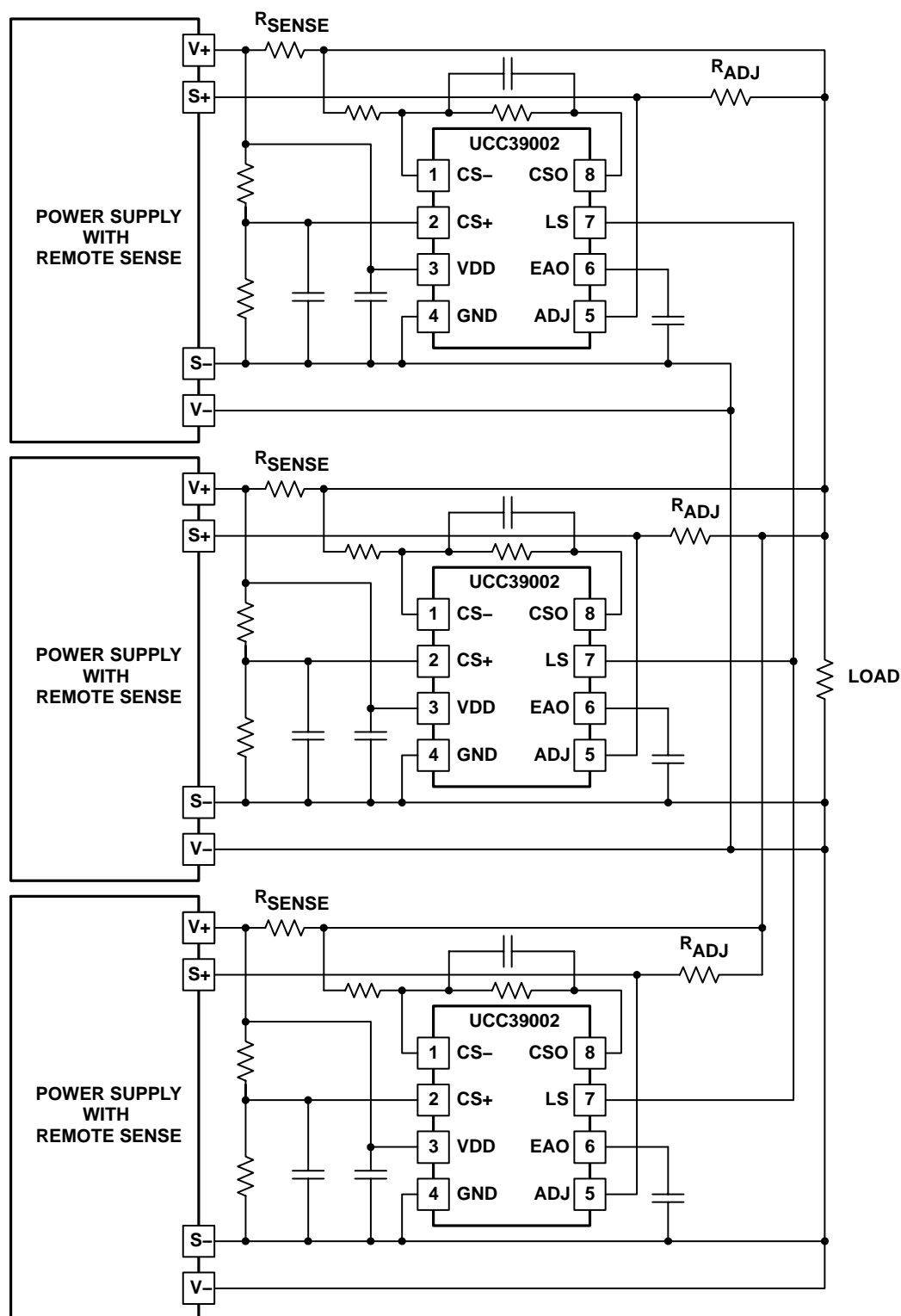
(1) Enables the load share bus at start-up.

(2) Ensured by design. Not production tested.

### TERMINAL FUNCTIONS

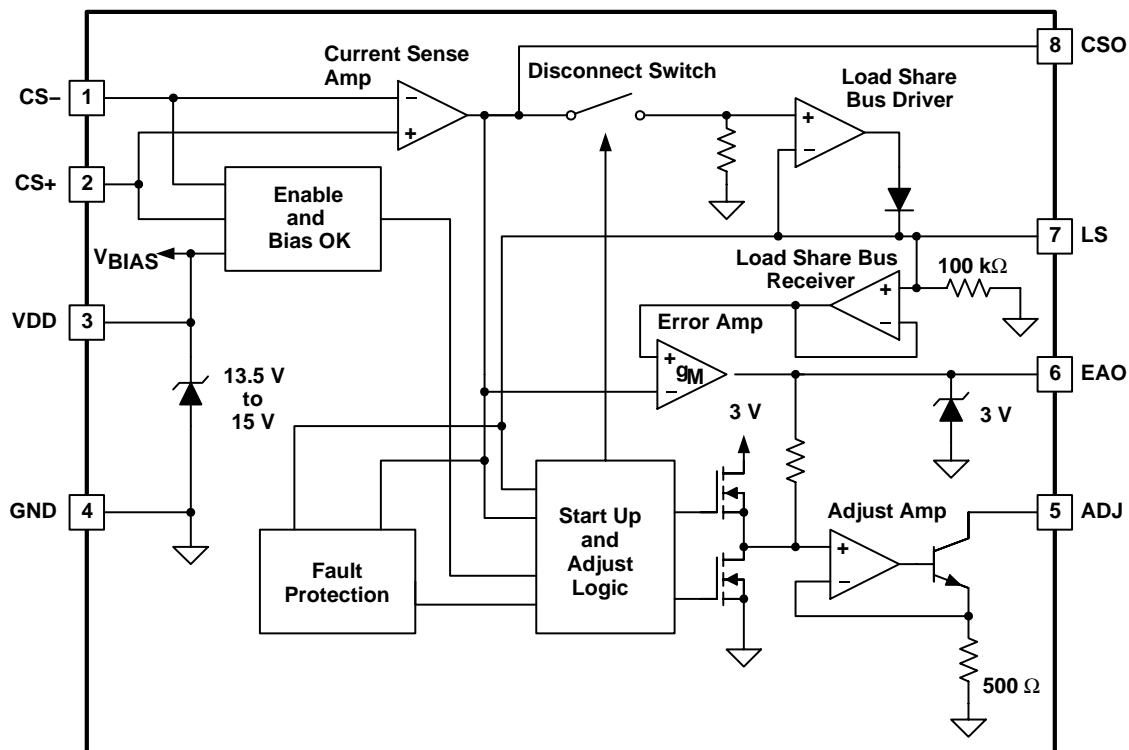
TERMINAL		I/O	DESCRIPTION
NAME	NO.		
ADJ	5	O	Adjust amplifier output. This is the buffered output of the error amplifier block to adjust output voltage of the power supply being controlled. This pin must always be connected to a voltage equal to or greater than $V_{EAO} + 1\text{ V}$ .
CS-	1	I	Current sense amplifier inverting input.
CS+	2	I	Current sense amplifier non-inverting input.
CSO	8	O	Current sense amplifier output.
EAO	6	O	Output for load share error amplifier. (Transconductance error amplifier.)
GND	4	-	Ground. Reference ground and power ground for all device functions.
LS	7	I/O	Load share bus. Output of the load share bus driver amplifier.
VDD	3	I	Power supply providing bias to the device.

# typical high-side current sensing application



UDG-01078

## functional block diagram



UDG-02086

## FUNCTIONAL DESCRIPTION

### differential current sense amplifier (CS+, CS–, CSO)

The UCC39002 features a high-gain and high-precision amplifier to measure the voltage across a low-value current sense resistor. Since the amplifier is fully uncommitted, the current sense gain is user programmable. The extremely low input offset voltage of the UCC39002 current sense amplifier makes it suitable to measure current information across a low value sense resistor. Furthermore, the input common mode range includes ground and the positive supply rail of the UCC39002 ( $V_{DD}$ ). Accordingly, the current sense resistor can be placed in the ground return path or in the positive output rail of the power supply  $V_O$  as long as  $V_O \leq V_{DD}$ .

### load share bus driver amplifier (CSO)

This is a unity-gain buffer amplifier to provide separation between the load share bus voltage and the output of the current sense amplifier. The circuit implements an ideal diode with virtually 0 V forward voltage drop by placing the diode inside the feedback loop of the amplifier. The diode function is used to automatically establish the role of the master module in the system. The UCC39002 which is assigned to be the master uses the load share bus driver amplifier to copy its output current information on to the load share bus.

All slave units, with lower output current levels by definition, have this “ideal diode” reversed biased ( $V_{CSO} < V_{LS}$ ). Consequently, the  $V_{CSO}$  and  $V_{LS}$  signals will be separated. That allows the error amplifier of the UCC39002 to compare its respective module’s output current to the master module’s output current and make the necessary corrections to achieve a balanced current distribution.

## FUNCTIONAL DESCRIPTION

Since the bus is always driven by a single load share bus driver amplifier, the number of modules ( $n$ ) are limited by the output current capability of the amplifier according to:

$$n = \frac{100 \text{ k}\Omega \times I_{\text{OUT,MIN}}}{V_{\text{LS,FULL\_SCALE}}} \quad (1)$$

where 100 k $\Omega$  is the input impedance of the LS pin as shown in the block diagram,  $I_{\text{OUT,MIN}}$  is given in the data sheet and  $V_{\text{LS,FULL\_SCALE}}$  is the maximum voltage on the load share bus at full load.

Note that the number of parallel units can be increased by reducing the full scale bus voltage, i.e. by reducing the current sense gain.

### load share bus receiver amplifier (LS)

The load share bus receiver amplifier is a unity gain buffer monitoring the load share bus voltage. Its primary purpose is to ensure that the load share bus is not loaded by the internal impedances of the UCC39002.

### error amplifier (EAO)

As pictured in the block diagram, the UCC39002 employs a transconductance also called  $g_M$  type error amplifier. The  $g_M$  amplifier was chosen because it requires only one pin, the output to be accessible for compensation.

The purpose of the error amplifier is to compare the average, per module current level to the output current of the respective module controlled by the UCC39002. It is accommodated by connecting the buffered  $V_{\text{LS}}$  voltage to its non-inverting input and the  $V_{\text{CSO}}$  signal to its inverting input. If the average per module current, represented by the load share bus is higher than the module's own output current, an error signal will be developed across the compensation components connected between the EAO pin and ground. The error signal is then used by the adjust amplifier to make the necessary output voltage adjustments to ensure equal output currents among the parallel operated power supplies.

In case the UCC39002 assumes the role of the master load share controller in the system or it is used in conjunction with a stand alone power module, the measured current signal on  $V_{\text{CSO}}$  is approximately equal to the  $V_{\text{LS}}$  voltage. To avoid erroneous output voltage adjustment, the input of the error amplifier incorporates a typically 25 mV offset to ensure that the inverting input of the error amplifier is biased higher than the non-inverting input. Consequently, when the two signals are equal, there will be no adjustment made and the initial output voltage set point is maintained.

### adjust amplifier output (ADJ)

A current proportional to the error voltage  $V_{\text{EAO}}$  on pin 6 is sunk by the ADJ pin. This current flows through the adjust resistor  $R_{\text{ADJ}}$  and changes the output voltage of the module controlled by the UCC39002. The amplitude of the current is set by the 500- $\Omega$  internal resistor between ground and the emitter of the amplifier's open collector output transistor according to Figure 1. The adjust current value is given as:

$$I_{\text{ADJ}} = \frac{V_{\text{EAO}}}{500 \text{ }\Omega} \quad (2)$$

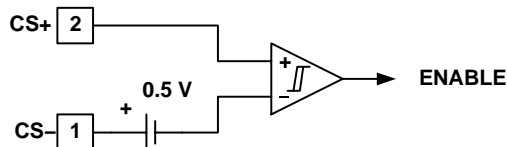
At the master module  $V_{\text{EAO}}$  is 0 V, thus the adjust current must be zero as well. This ensures that the output voltage of the master module remains at its initial output voltage set point at all times.

Furthermore, at insufficient bias level, during a fault or when the UCC39002 is disabled, the non-inverting input of the adjust amplifier is pulled to ground to prevent erroneous adjustment of the module's output voltage by the load share controller.

## FUNCTIONAL DESCRIPTION

### enable function (CS+, CS–)

The two inputs of the current sense amplifier are also used for implementing an ENABLE function. During normal operation  $CS- = CS+$  and the internal offset added between the  $CS-$  voltage and the inverting input of the enable comparator ensures that the UCC39002 is always enabled. By forcing the  $CS-$  pin approximately 0.5-V above the  $CS+$  pin, the UCC39002 can be forced into a disable mode. While disabled, the UCC39002 disconnects itself from the load share bus and its adjust current is zero.

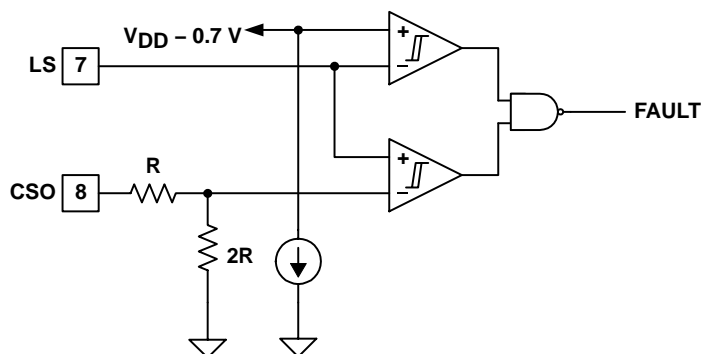


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**Figure 1. Enable Comparator**

### fault protection

Accidentally, the load share bus might be shorted to ground or to the positive bias voltage of the UCC39002. These events might result in erroneous output voltage adjustment. For that reason, the load share bus is continuously monitored by a window comparator as shown in Figure 2.



UDG-02088

**Figure 2. Fault Protection Comparators**

The FAULT signal is handled by the start up and adjust logic which pulls the non-inverting input of the adjust amplifier low when the FAULT signal is asserted.



## FUNCTIONAL DESCRIPTION

### start up and adjust logic

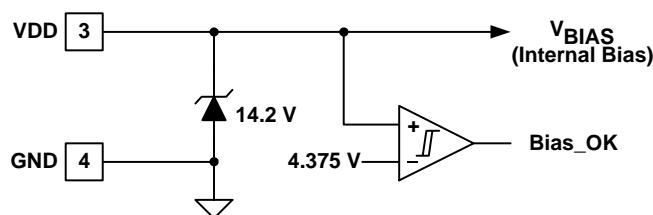
The start up and adjust logic responds to unusual operating conditions during start up, fault and disable. Under these circumstances the information obtainable by the error amplifier of the UCC39002 is not sufficient to make the right output voltage adjustment, therefore the adjust amplifier is forced to certain known states. Similarly, the driver amplifier of UCC39002 is disabled during these conditions.

During start up, the load share driver amplifier is disabled by the disconnect switch and the adjust amplifier is forced to sink the maximum current through the adjust resistor. This operating mode ensures that the module controlled by the UCC39002 will be able to engage in sharing the load current since its output will be adjusted to a sufficiently high voltage. Both the load share driver and the adjust amplifiers revert to normal operation as soon as the measured current exceeds 80% of the average per module current level represented by the bus voltage.

In case of a fault shorting the load share bus to ground or to the bias of the UCC39002 the load share bus driver and the adjust amplifiers are disabled. The same action takes place when the UCC39002 is disabled using the CS+ and CS– pins or when the bias voltage is below the minimum operating voltage.

### bias and bias OK circuit (VDD)

The UCC39002 is built on a 15-V, high performance BiCMOS process. Accordingly the maximum voltage across the V<sub>DD</sub> and GND pins (pin 3 and 4 respectively) is limited to 15 V. The recommended maximum operating voltage is 13.5 V which corresponds to the tolerance of the on-board 14.2-V Zener clamp circuit. In case the bias voltage could exceed the 13.5-V limit, the UCC39002 should be powered through a current limiting resistor. The current into the V<sub>DD</sub> pin must be limited to 10 mA as listed in the absolute maximum ratings table.



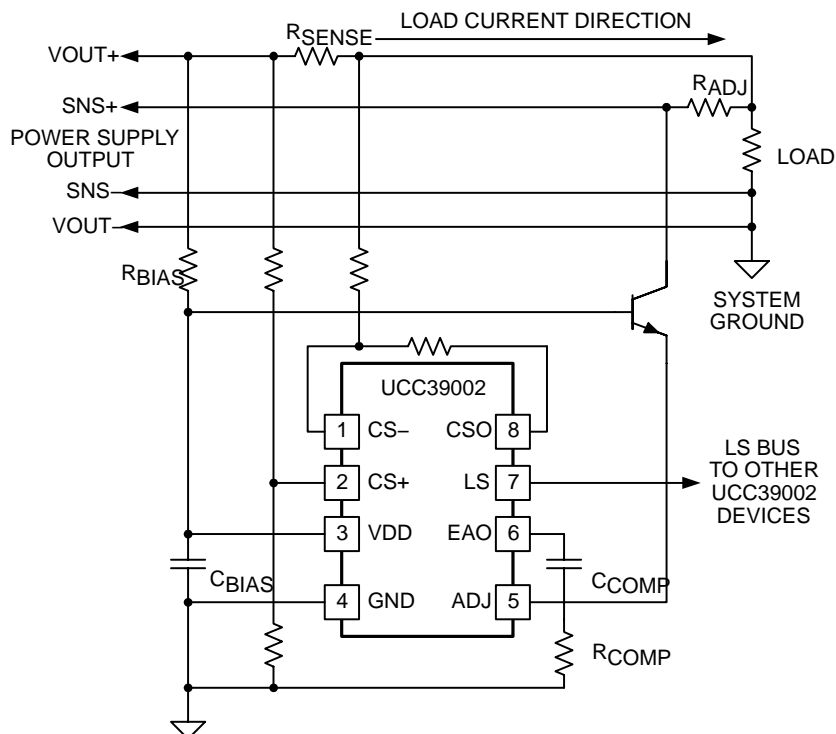
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**Figure 3. V<sub>DD</sub> Clamp and Bias Monitor**

The UCC39002 does not have an undervoltage lockout circuit. The bias OK comparator works as an enable function with a 4.375-V threshold. While V<sub>DD</sub> < 4.375 V the load share control functions are disabled. While this might be inconvenient for some low voltage applications it is necessary to ensure high accuracy. The load share accuracy is dependent on working with relatively large signal amplitudes on the load share bus. If the internal offsets, current sense error and ground potential difference between the UCC39002 controllers are comparable in amplitude to the load share bus voltage, they can cause significant current distribution error in the system. The maximum voltage on the load share bus is limited approximately 1.7-V below the bias voltage level (V<sub>DD</sub>) which would result in an unacceptably low load share bus amplitude therefore poor accuracy at low V<sub>DD</sub> levels. To circumvent this potential design problem, the UCC39002 won't operate below the above mentioned 4.375-V bias voltage threshold. If the system does not have a suitable bias voltage available to power the UCC39002, it is recommended to use an inexpensive charge pump which can generate the bias voltage for all the UCC39002s in the load share system.

## FUNCTIONAL DESCRIPTION

The maximum  $V_{DD}$  of the UCC39002 is 15 V. For higher-voltage applications, use the application solution as recommended in Figure 4. A Zener clamp on the VDD pin is provided internally so the device can be powered from higher voltage rails using a minimum number of external components.



UDG-01077

**Figure 4. High Voltage Application**

The following is a practical step-by-step design procedure on how to use the UCC39002 to parallel power modules for load sharing.

- $V_{OUT}$  = nominal output voltage of the modules to be paralleled
- $I_{OUT(max)}$  = maximum output current of each module to be paralleled
- $\Delta V_{ADJ}$  = maximum output voltage adjustment range of the power modules to be paralleled
- $N$  = number of modules

A typical high side application for a single module is shown in Figure 5 and is repeated for each module to be paralleled.

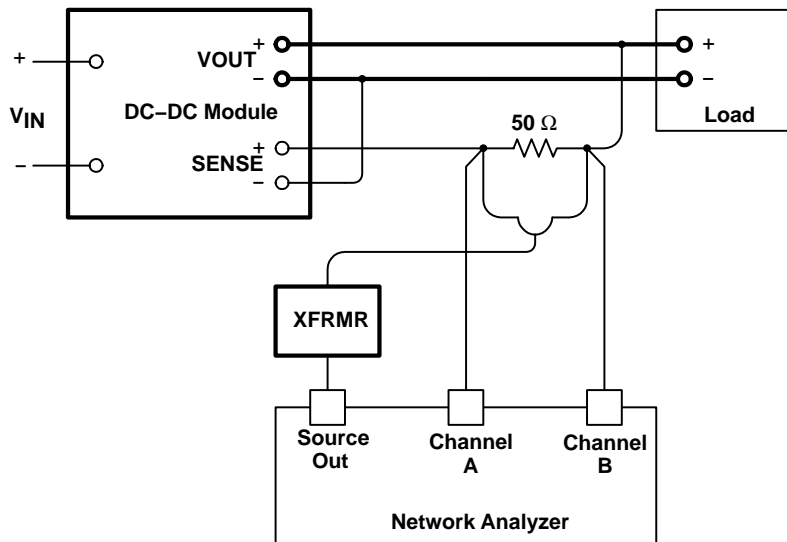


In Figure 5, P1 represents the output voltage terminals of the module, S1 represents the remote sense terminals of the module, and a signal on the SB2 terminal will enable the disconnect feature of the device. The load share bus is the common bus between all of the paralleled load share controllers. VDD must be decoupled with a good quality ceramic capacitor returned directly to GND.

## DESIGN PROCEDURE

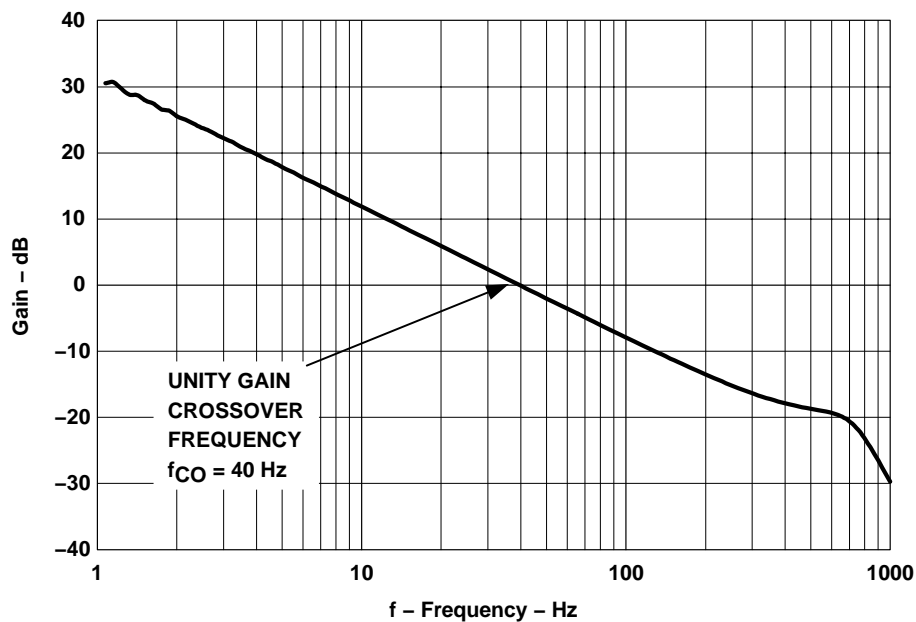
### measuring the modules' loop

Using the configuration in Figure 6, measure the unity gain crossover frequency of the power modules to be paralleled. A typical resultant bode plot is shown in Figure 7.



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**Figure 6. Unity Gain Crossover Frequency Measurement Connection Diagram**



**Figure 7. Power Module Bode Plot**

## DESIGN PROCEDURE

### the sense resistor

Selection of the sense resistor is limited by its voltage drop at maximum module output current. This voltage drop should be much less than the voltage adjustment range of the module:

$$I_{OUT(max)} \times R_{SENSE} \ll \Delta V_{ADJ(max)} \quad (3)$$

Other limitations for the sense resistor are the desired minimum power dissipation and available component ratings.

### the CSA gain

The gain of the current sense amplifier is configured by the compensation components between Pin 1, CS–, and Pin 8, CSO, of the load share device. The voltage at the CSO pin is limited by the saturation voltage of the internal current sense amplifier and must be at least two volts less than VDD:

$$V_{CSO(max)} < V_{DD} - 2 \text{ V} \quad (4)$$

The maximum current sense amplifier gain is equal to:

$$A_{CSA} = \frac{V_{CSO}}{(R_{SENSE} \times I_{OUT(max)})} \quad (5)$$

Referring to Figure 5, the gain is equal to R16/R15 and a high-frequency pole, configured with C13, is used for noise filtering. This impedance is mirrored at the CS+ pin of the differential amplifier as shown.

The current sense amplifier output voltage,  $V_{CSO}$ , serves as the input to the unity gain LS bus driver. The module with the highest output voltage forward biases the internal diode at the output of the LS bus driver and determine the voltage on the load share bus,  $V_{LS}$ . The other modules act as slaves and represent a load on the  $I_{VDD}$  of the module due to the internal 100-k $\Omega$  resistor at the LS pin. This increase in supply current for the master module is equal to  $N(V_{LS}/100 \text{ k}\Omega)$ .

### determining R<sub>ADJUST</sub>

The Sense+ terminal of the module is connected to the ADJ pin of the load-share controller. By placing a resistor between this ADJ pin and the load, an artificial Sense+ voltage is created from the voltage drop across  $R_{ADJUST}$  due to the current sunk by the internal NPN transistor. The voltage at the ADJ pin must be maintained at approximately 1 V above the voltage at the EAO pin. This is necessary in order to keep the transistor at the output of the internal adjust amplifier from saturating. To fulfill this requirement,  $R_{ADJUST}$  is first calculated using the following equation:

$$R_{ADJUST} \geq \frac{\left[ \Delta V_{ADJ(max)} - (I_{OUT(max)} \times R_{SENSE}) \right] \times 500 \Omega}{\left[ V_{OUT} - \Delta V_{ADJ(max)} + (I_{OUT(max)} \times R_{SENSE}) - 1 \text{ V} \right]} \quad (6)$$

## DESIGN PROCEDURE

Also needed for consideration is the actual adjust pin current. The maximum sink current for the ADJ pin,  $I_{ADJ(max)}$ , is 6 mA as determined by the internal 500- $\Omega$  emitter resistor and 3-V clamp. The value of adjust resistor,  $R_{ADJUST}$ , is based upon the maximum adjustment range of the module,  $\Delta V_{ADJ(max)}$ . This adjust resistor is determined using the following formula:

$$R_{ADJUST} \geq \frac{\left[ \Delta V_{ADJ(max)} - (I_{OUT(max)} \times R_{SENSE}) \right]}{I_{ADJ(max)}} \quad (7)$$

By selecting a resistor that meets both of these minimum requirements, the ADJ pin will be at least 1 V greater than the EAO voltage and the adjust pin sink current will not exceed its 6 mA maximum.

### error amplifier compensation

The total load-share loop unity-gain crossover frequency,  $f_{CO}$ , should be set at least one decade below the measured crossover frequency of the paralleled modules previously measured,  $f_{CO(module)}$ . (See Figure 7) Compensation of the transconductance error amplifier is accomplished by placing the compensation resistor,  $R_{EAO}$ , and capacitor,  $C_{EAO}$ , between EAO and GND. The values of these components is determined using equations (8) and (13).

$$C_{EAO} = \left( \frac{g_M}{\pi f_{CO}} \right) (A_{CSA}) (A_V) (A_{ADJ}) (A_{PWR}(f_{CO})) \quad (8)$$

Where:

- $g_M$  is the transconductance of the error amplifier, typically 14 mS,
- $f_{CO}$  is equal to the desired crossover frequency in Hz of the load share loop, typically  $f_{CO} (module)/10$ ,
- $A_{CSA}$  equals  $R_{16}/R_{15}$ ,
- $A_V$  is the voltage gain, equal to  $R_{SENSE}/R_{LOAD}$ ,
- $A_{ADJ}$  is the gain associated with the adjust amplifier, equal to  $R_{ADJUST}/500 \Omega$ ,
- $A_{PWR}(f_{CO})$  is the measured gain of the power module at the desired load share crossover frequency, converted from dB to V/V

$$A_{CSA} = \frac{R_{16}}{R_{15}} \quad (9)$$

$$A_V = \frac{R_{SENSE}}{R_{LOAD}} \quad (10)$$

$$A_{ADJ} = \frac{R_{ADJUST}}{500 \Omega} \quad (11)$$

$$A_{PWR}(f_{CO}) = \text{from power module's Bode plot (Fig. 7)} \quad (12)$$

Once the  $C_{EAO}$  capacitor is determined,  $R_{EAO}$  is selected to achieve the desired loop response:

$$R_{EAO} = \frac{1}{\left[ 2\pi (C_{EAO}) (f_{CO}) \right]} \quad (13)$$

## DESIGN PROCEDURE

### references

For further details, refer to the following document:

- Reference Design, *48- $V_{IN}$ , 12- $V_{OUT}$  Loadshare System Using UCC39002 with Three DC/DC PH-100S4 Modules*, Texas Instruments Literature No. SLUA270

For a more complete description of general load sharing topics, refer to the following documents.

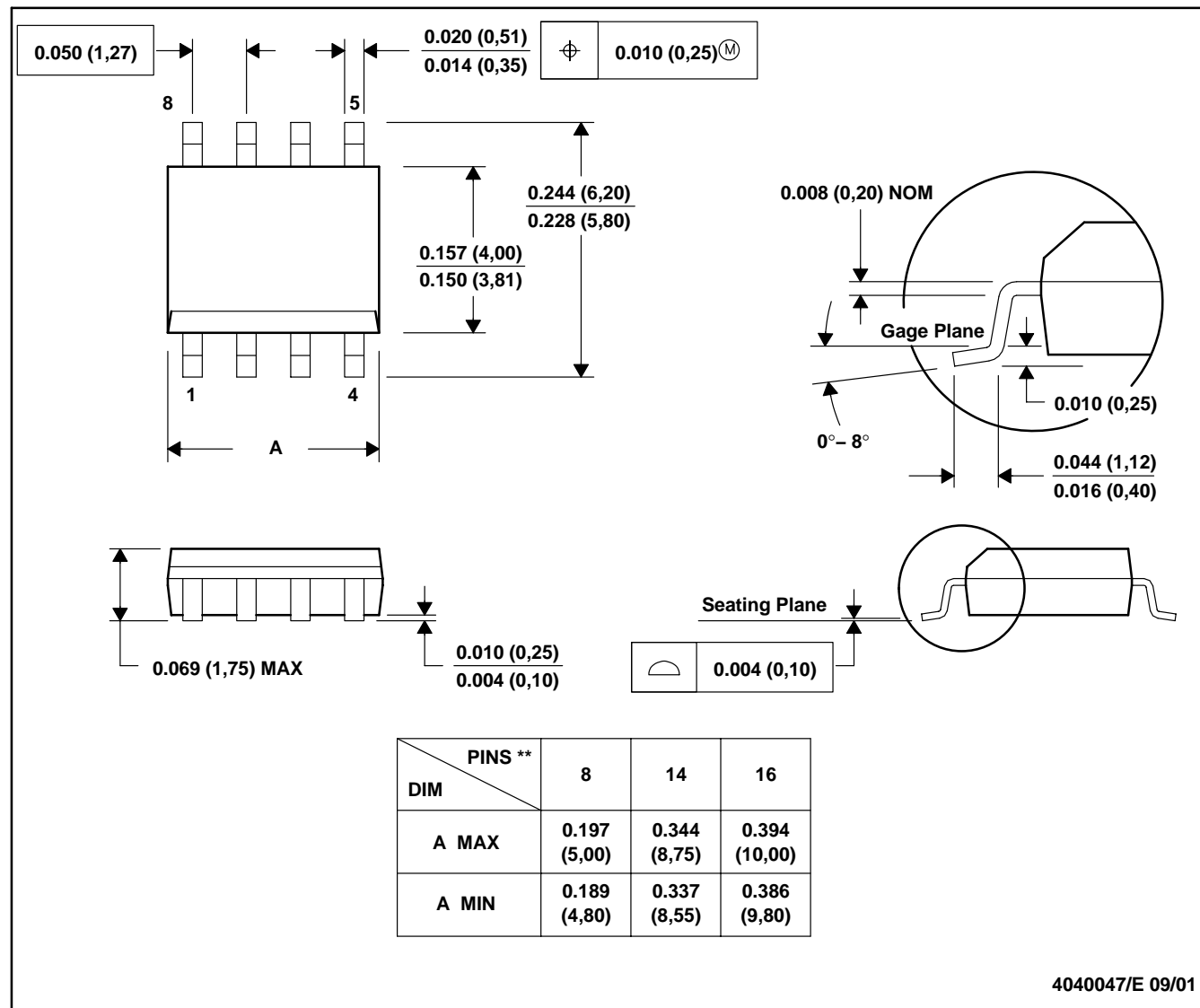
- Application Note, *The UC3902 Load Share Controller and Its Performance in Distributed Power Systems*, TI Literature No. SLUA128
- Application Note, *UC3907 Load Share IC Simplifies Parallel Power Supply Design*, TI Literature No. SLUA147

# MECHANICAL DATA

**D (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

**8 PINS SHOWN**



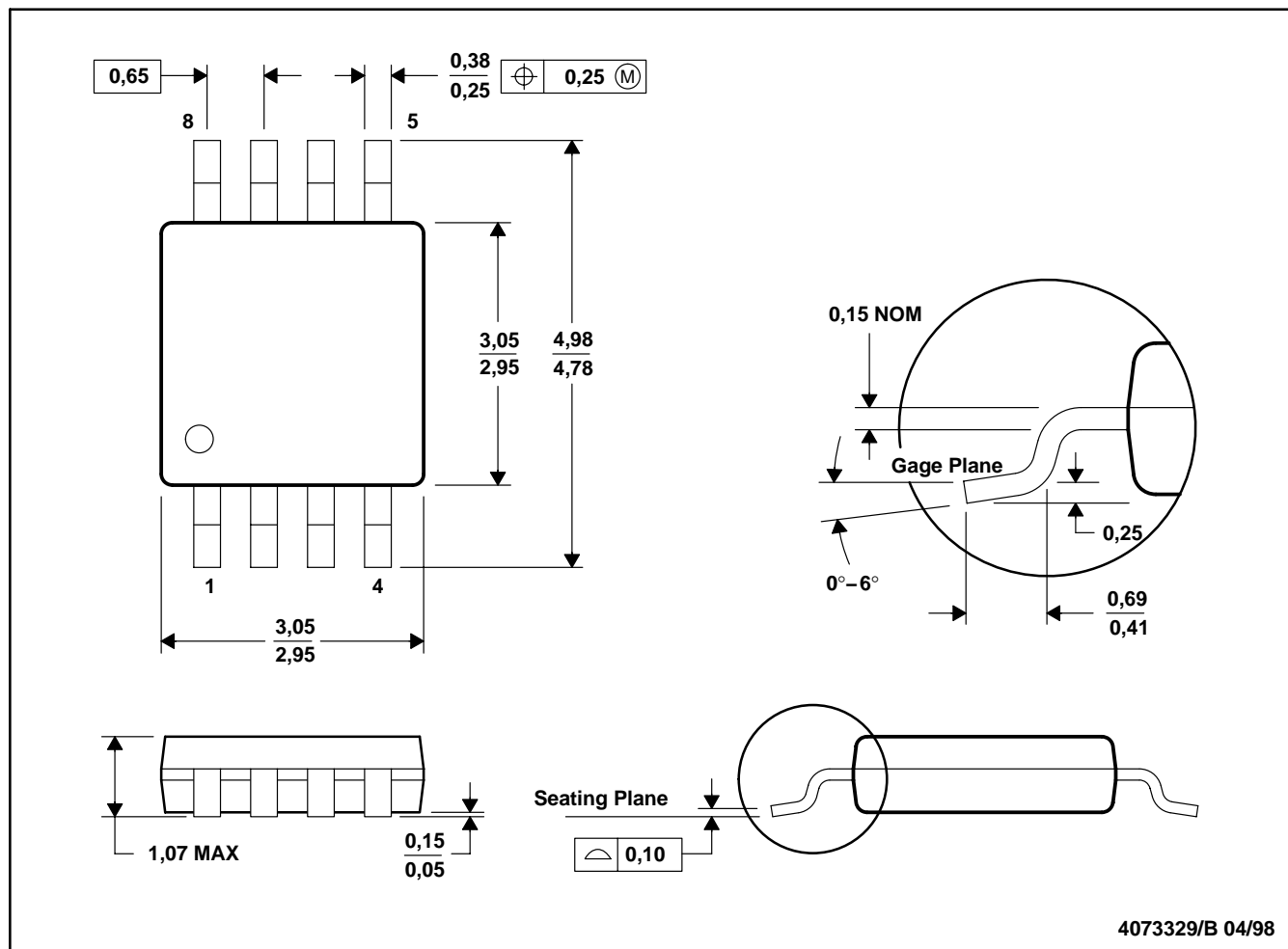
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 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MS-012



# MECHANICAL DATA

DGK (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

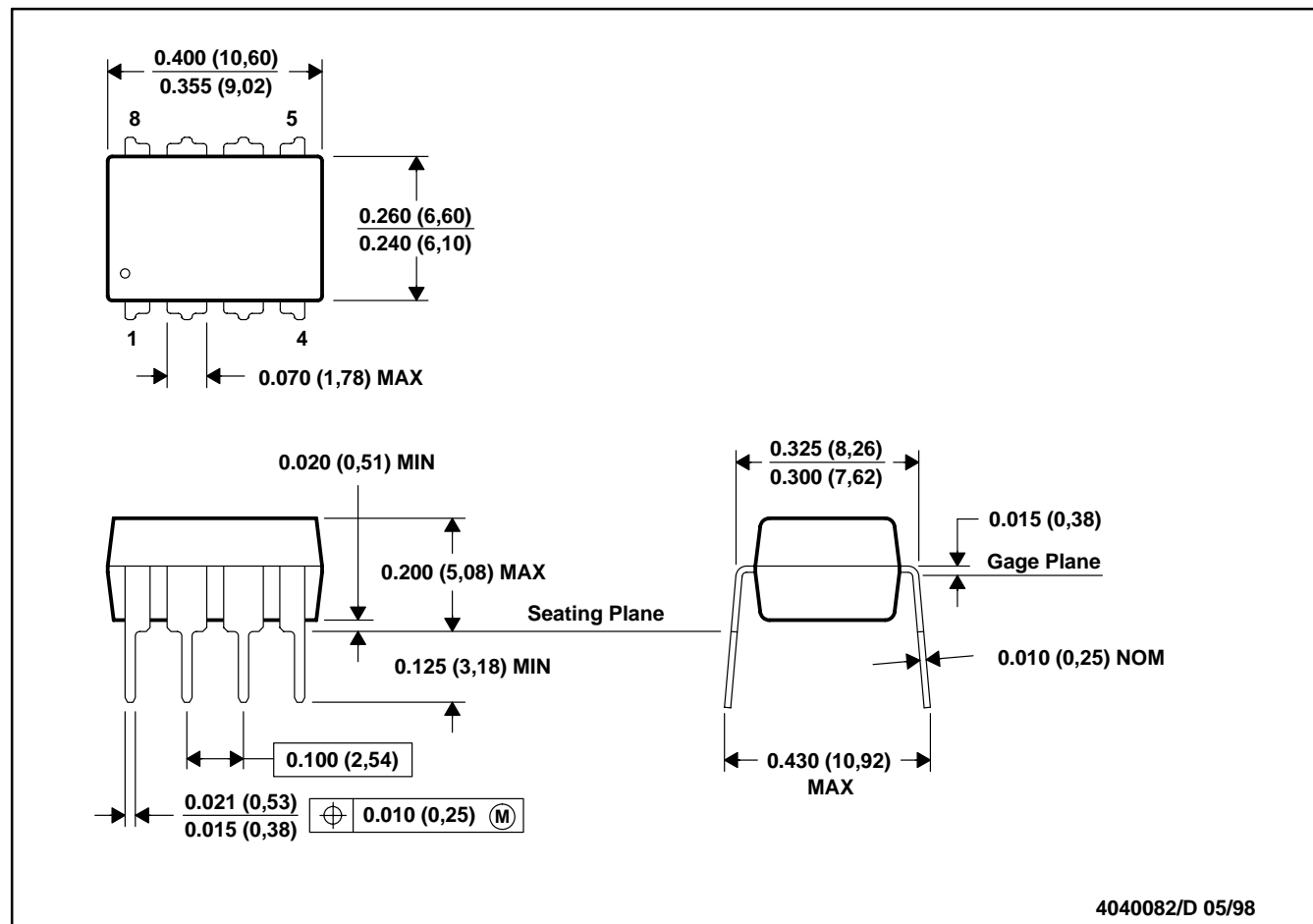


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**MECHANICAL DATA**

**P (PDIP)**

**PLASTIC DUAL-IN-LINE**



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**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
UCC29002D	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
UCC29002DGK	ACTIVE	MSOP	DGK	8	80	None	CU SNPB	Level-1-220C-UNLIM
UCC29002DGKR	ACTIVE	MSOP	DGK	8	2500	None	CU SNPB	Level-1-220C-UNLIM
UCC29002DR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
UCC29002P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
UCC29002PE4	ACTIVE	PDIP	P	8	50	None	Call TI	Call TI
UCC39002D	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
UCC39002DGK	ACTIVE	MSOP	DGK	8	80	None	CU NIPDAU	Level-1-220C-UNLIM
UCC39002DGKR	ACTIVE	MSOP	DGK	8	2500	None	CU NIPDAU	Level-1-220C-UNLIM
UCC39002DR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
UCC39002P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
UCC39002PE4	ACTIVE	PDIP	P	8	50	None	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**None:** Not yet available Lead (Pb-Free).

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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## P (R-PDIP-T8)

## PLASTIC DUAL-IN-LINE

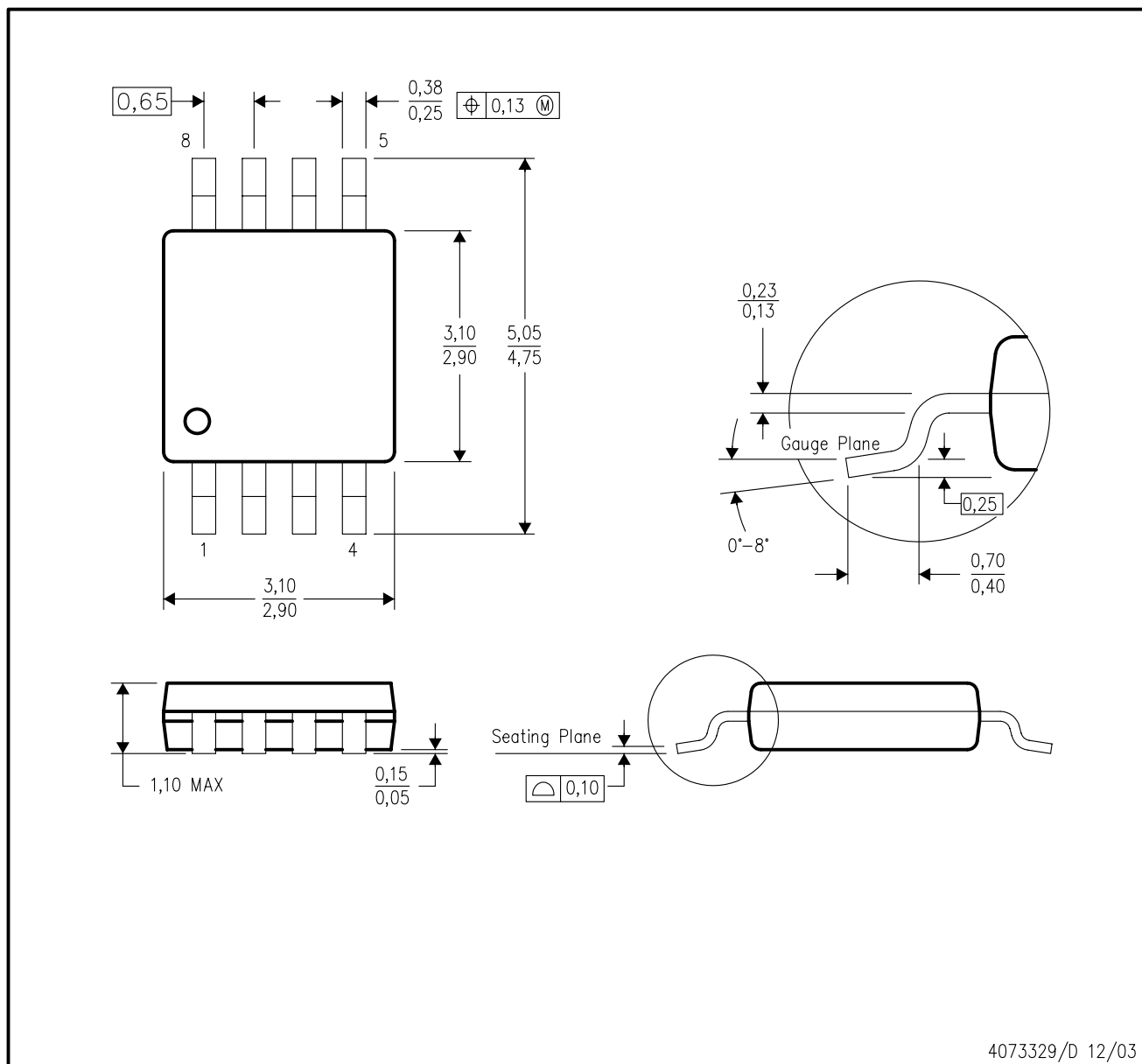


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For the latest package information, go to [http://www.ti.com/sc/docs/package/pkg\\_info.htm](http://www.ti.com/sc/docs/package/pkg_info.htm)

## DGK (S-PDSO-G8)

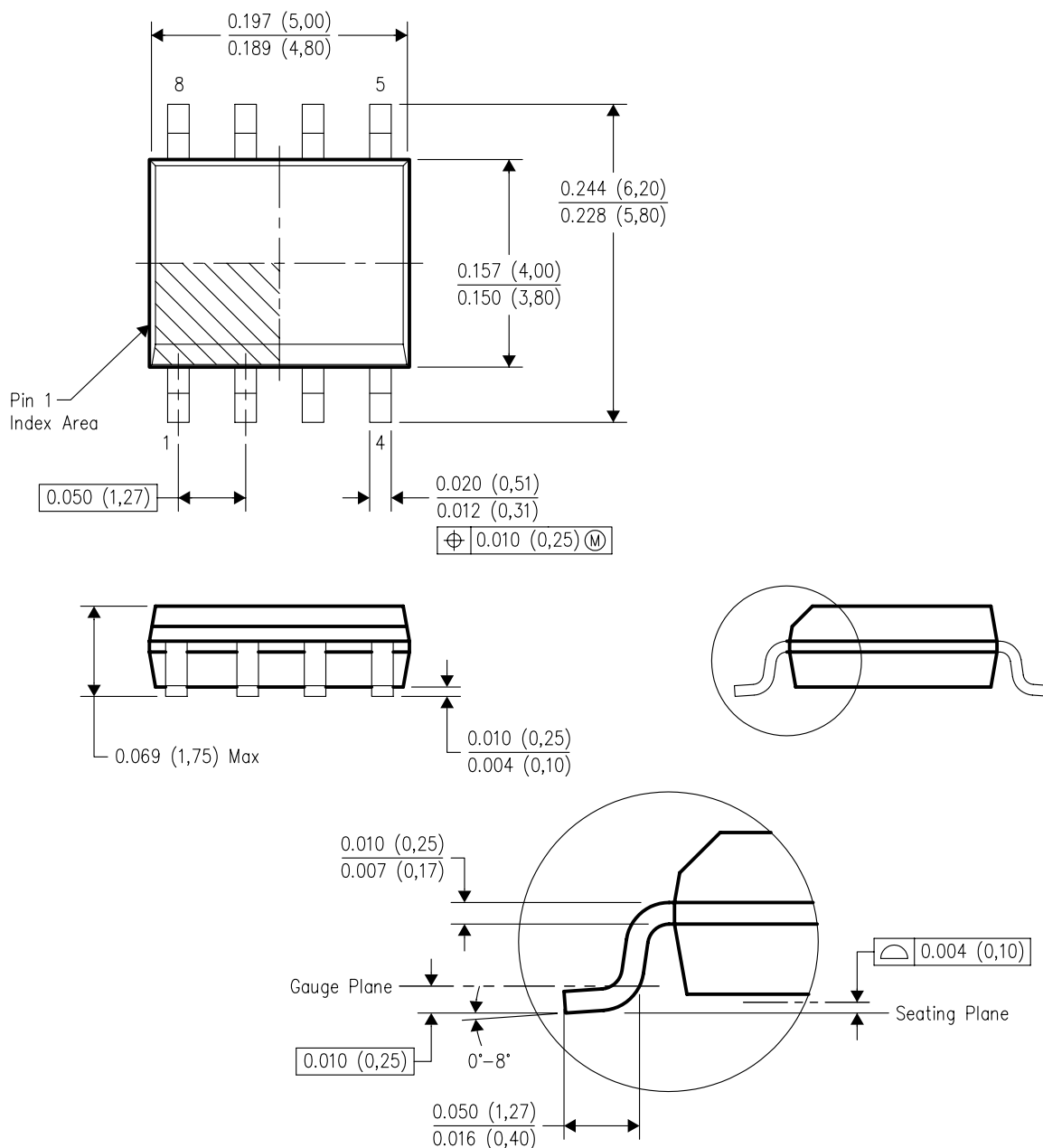
## PLASTIC SMALL-OUTLINE PACKAGE



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D (R-PDSO-G8)

# PLASTIC SMALL-OUTLINE PACKAGE



4040047-2/F 07/2004

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